## BUSSMANN SERIES

# 1245HC

## Fast-acting high current brick fuse



#### **Product features**

- 4818 (1245 metric) size
- · Fast-acting high current brick fuse
- · Compact design utilizes less board space
- Ceramic tube, silver plated brass end cap construction
- Designed to UL248-1/14
- Moisture sensitivity level (MSL): 1

#### **Applications**

Primary and secondary circuit protection:

- · Server and desktop power supplies
- · Energy storage systems
- E-bikes
- · LED and general lighting
- · Power distribution units
- · Gaming console systems
- Voltage Regulator Module (VRM)
- · Point-of-load (POL) protection
- · High power battery packs
- · Storage system power
- Basic power supplies

#### **Agency information**

cURus Recognition file number: E91958, Guide JFHR2/JFHR8

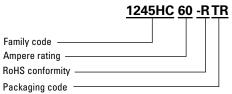


#### **Environmental compliance**





## Ordering part number



#### **Packaging prefix**

TR (1000 parts on a 13" diameter tape and reel)



#### **Electrical characteristics**

Amp Rating	100% In minimum	350% In maximum
60 A ~ 100 A	4 hours	10 seconds

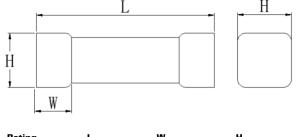
#### **Product specifications**

Part number	Current rating (A)	Voltage (Vac)	rating (Vdc)	Interrupti @ rated vo (A) Vac	ng rating oltage <sup>1,2</sup> (A) Vdc	Typical resistance (mΩ)	Typical voltage drop (mV)	Typical pre-arcing³ I²t (A²s)	Part marking
1245HC60-R	60	125	80 <sup>4</sup> 72 63 32	500	1000	0.58	65	950	60 A
1245HC80-R	80	125	72 63 32	500	1000	0.44	60	1700	80 A
1245HC100-R	100	125	72 63 32	500	1000	0.29	55	5000	100 A

- 1. AC Interrupting rating (Measured at designated voltage, 100% power factor random closing)
- 2. DC Interrupting rating (Measured at designated voltage, time constant of less than 50 microseconds, battery source)
- 3. Typical pre-arcing I2t are measured at 10ln Current, DC battery bank, but not exceeding the interrupting rating, time constant of calibrated circuit less than 50 microseconds)
- 4. Internal qualification for 60 A @ 80 Vdc, UL Approval is pending

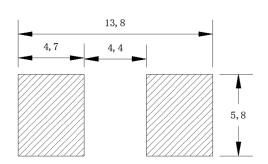
## Dimensions- mm

Drawing not to scale



Rating	L	W	Н
60 A ~ 100 A	12.30 ± 0.40	2.70 ± 0.20	4.50 ± 0.20

#### Recommended pad layout



60 A - 70 A: Recommend trace thickness is 3 oz; the minimum trace width is 22 mm 80 A - 100 A: Recommend trace thickness is 6 oz; the minimum trace width is 33 mm Recommended stencil thickness is 0.15 mm

#### **General specifications**

Operating temperature: -55 °C to +125 °C with proper derating factor applied

Thermal shock: MIL-STD-202, Method 107G -55 °C/+125 °C. Note: Number of cycles required 100 times

Humidity bias: MIL-STD-202, Method 103 +85 °C/85% RH, 1000 hours

Mechanical shock: Figure 1 of Method 213. Condition C, 100 g, 6 ms

Mechanical vibration: MIL-STD-202G, Method 20, 2 hours each of 3 orientations. Test from 10-55 Hz in 1 minute

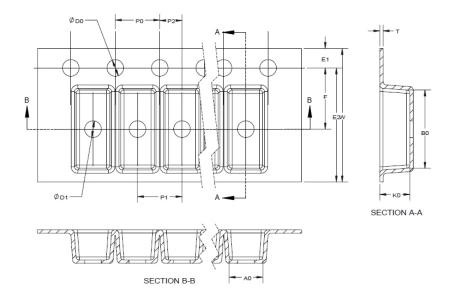
Resistance to solder heat: MIL-STD-202G Method 210F, condition D (+260 °C,10 s)

Solderability test: J-STD-002, Method B1 Steam aging 1 hour, Solder temperature  $\pm 255 \pm 5$  °C, solder immersion time 5 s

High temperature operating life: MIL-STD-202 Method 108 Condition D, Steady state TA= +70 °C at 60% rated current

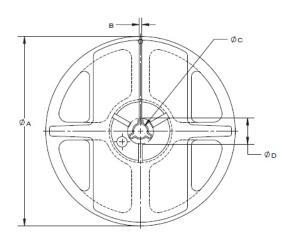
## Packaging information - mm

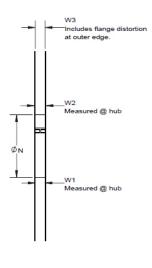
1000 parts per 13" diameter reel



Dimension	millimeter
W	24.00
F	11.50
E1	1.75
E2	N/A
P0	4.00
P1	8.00
P2	2.00
DO DO	1.50
D1	1.50
A0	4.85
B0	12.75
KO	4.90
T	0.40

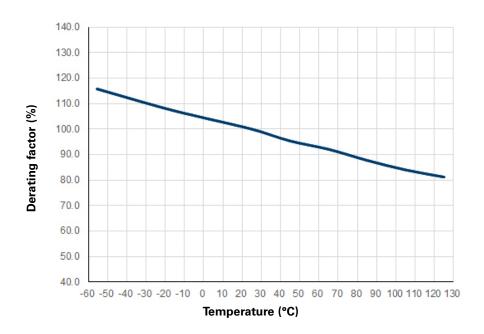
## Reel dimension- mm



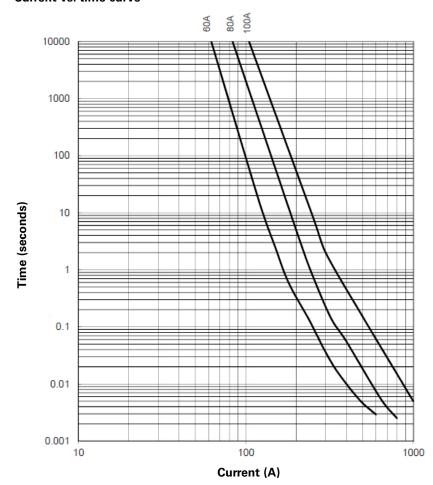


Dimension	millimeter
A	330 ± 1
В	$2.5 \pm 0.2$
С	13.5 ± 0.2
D	N/A
N	100 ± 0.5
W1	24.8 +5/-0.5
W2	30.4 max
W3	N/A

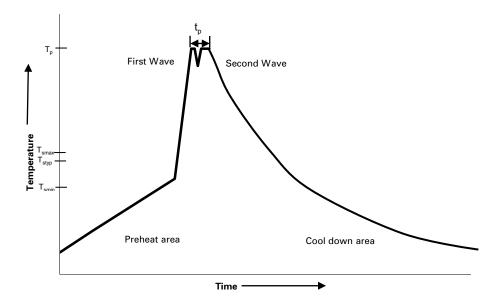
### Temperature derating curve



#### Current vs. time curve



## Wave solder profile



### Reference EN 61760-1:2006

Profile feat	ture	Standard SnPb solder	Lead (Pb) free solder
Preheat	• Temperature min. (T <sub>smin</sub> )	100 °C	100 °C
	• Temperature typ. (T <sub>styp</sub> )	120 °C	120 °C
	• Temperature max. (T <sub>smax</sub> )	130 °C	130 °C
	Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	70 seconds	70 seconds
$\Delta$ preheat to	max Temperature	150 °C max.	150 °C max.
Peak tempera	ature (Tp)*	235 °C − 260 °C	250 °C – 260 °C
Time at peak	temperature (t <sub>p</sub> )	10 seconds max 5 seconds max each wave	10 seconds max 5 seconds max each wave
Ramp-down r	ate	~ 2 K/s min ~3.5 K/s typ ~5 K/s max	~ 2 K/s min ~3.5 K/s typ ~5 K/s max
Time 25 °C to	25 °C	4 minutes	4 minutes

#### Manual solder

+350 °C (4-5 seconds by soldering iron), generally manual/hand soldering is not recommended.

#### Solder reflow profile

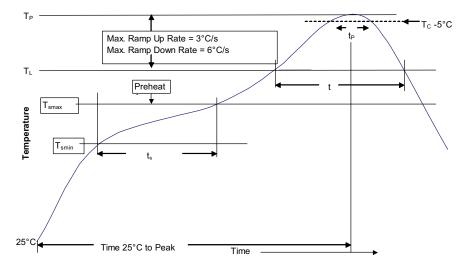


Table 1 - Standard SnPb solder (T<sub>C</sub>)

Package thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) free solder (T<sub>C</sub>)

Package thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

#### Reference J-STD-020

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat and soak • Temperature min. (T <sub>smin</sub> )	100 °C	150 °C
Temperature max. (T <sub>smax</sub> )	150 °C	200 °C
• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 seconds	60-120 seconds
Ramp up rate $T_L$ to $T_p$	3 °C/ second max.	3 °C/ second max.
Liquidous temperature (TL) Time (t <sub>L</sub> ) maintained above T <sub>L</sub>	183 °C 60-150 seconds	217 °C 60-150 seconds
Peak package body temperature (Tp)*	Table 1	Table 2
$\overline{\text{Time } (t_p)^* \text{ within 5 °C of the specified classification temperature } (T_c)}$	20 seconds*	30 seconds*
Ramp-down rate (T <sub>p</sub> to T <sub>L</sub> )	6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

<sup>\*</sup> Tolerance for peak profile temperature (T<sub>n</sub>) is defined as a supplier minimum and a user maximum.

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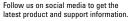
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